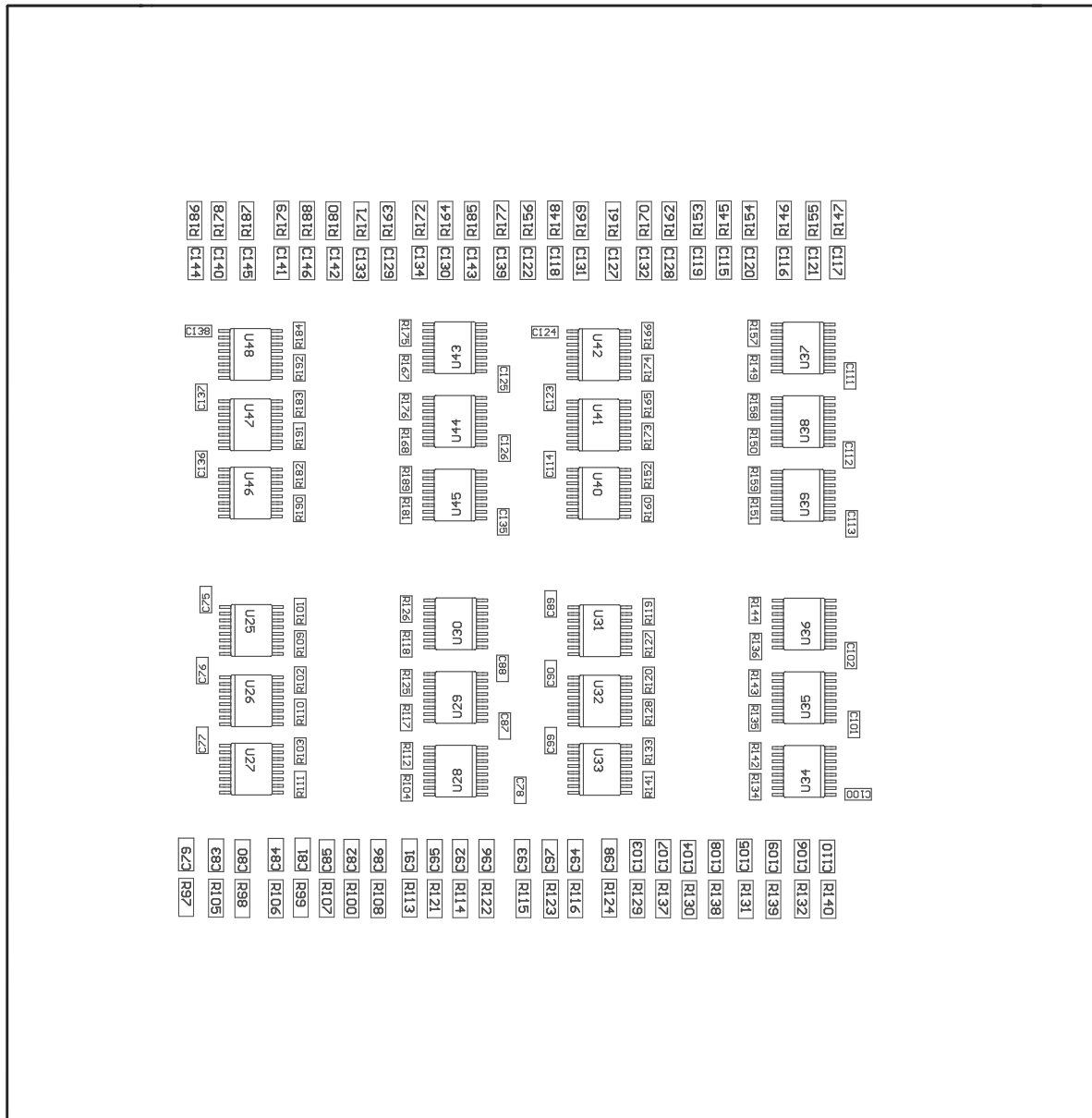


LBL1

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-060014	REV: E1	SUN REV: Not In VersionControl
M1 Board Outline	TID #: TIDA-060014		
PLOT NAME = Top Layer Assembly Drawing	GENERATED : 6/19/2018	11:00:37 AM	TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM BOTTOM SIDE	BOARD #:	TIDA-060014	REV:	E1	SUN REV: Not In VersionControl
	TID #:	TIDA-060014	IM Board Outline		
PLOT NAME = Bottom layer Assembly Drawing	GENERATED	: 6/19/2018	11:00:39 AM	TEXAS INSTRUMENTS	

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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